



Description

The PlasmaPro®100 Cobra is a modular plasma processing etch tool with semi-automatic loading system. The PlasmaPro®100 Cobra can process a wide range of wafer sizes, from small wafer pieces up to 100 mm (4") diameter. A precise flow of one or more process gases is supplied to the chamber from a gas pod, then the tool uses RF power to create a plasma inside the process chamber. The reactive ionic species generated within the plasma are guided onto the front surface of the wafers.

Specifications / Capabilities

Wafer size : Up to 4in Dia wafer

Maximal RF power is limited to 300 W and ICP power -3kW.

Etch materials : Al₂O₃, Quartz, SiN, ITO, TiO₂, Al , Cr

Gases

C₄F₈, SF₆, Ar, O₂, CHF₃, N₂O, He, Cl₂, BCl₃, C₂H₄

Link

<https://www.oxinst.com/>

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